

## **ABSTRACT**

An electrical conducting structure including an integrated circuit, a substrate, and a plurality of bumps, wherein at least one bump comprises a first conductive part connected to the integrated circuit at one end; a second conductive part connected to the integrated circuit at one end; a conductive connection part connecting the first conductive part and the second conductive part; a first insulation part surrounding the first conductive part and the second conductive part; and a second insulation part located between the first conductive part and the second conductive part.